

# N-Channel 100-V (D-S) MOSFET

| PRODUCT SUMMARY          |                                |                    |  |  |  |
|--------------------------|--------------------------------|--------------------|--|--|--|
| V <sub>(BR)DSS</sub> (V) | $R_{DS(on)}(\Omega)$           | I <sub>D</sub> (A) |  |  |  |
| 100                      | 0.127at V <sub>GS</sub> = 10 V | 18                 |  |  |  |

### **FEATURES**

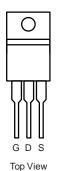
- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R<sub>g</sub> Tested

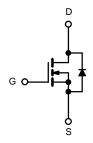


### **APPLICATIONS**

• Isolated DC/DC Converters







N-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b>                    | <b>S</b> T <sub>C</sub> = 25 °C, unless oth | erwise noted                      |             |      |  |
|--|---|-----------------------------------|-------------|------|--|
| Parameter  |   | Symbol                            | Limit       | Unit |  |
| Drain-Source Voltage                               |   | V <sub>DS</sub>                   | 100         | V    |  |
| Gate-Source Voltage                                |   | V <sub>GS</sub>                   | ± 20        | V    |  |
| Continuous Drain Current (T <sub>J</sub> = 175 °C) | T <sub>C</sub> = 25 °C                      | 1_                                | 18          | ^    |  |
|  | T <sub>C</sub> = 125 °C                     | I <sub>D</sub>                    | 15          |      |  |
| Pulsed Drain Current                               |   | I <sub>DM</sub>                   | 68          | Α    |  |
| Avalanche Current                                  | L = 0.1 mH                                  | I <sub>AS</sub>                   | 18          |      |  |
| Single Pulse Avalanche Energy <sup>b</sup>         | L = 0.1 IIII1                               | E <sub>AS</sub>                   | 200         | mJ   |  |
| Mariana Para Pinainatianh                          | T <sub>C</sub> = 25 °C                      | D.                                | 105         | 10/  |  |
| Maximum Power Dissipation <sup>b</sup>             | T <sub>A</sub> = 25 °C <sup>d</sup>         | $ P_D$                            | 3.75        | W    |  |
| Operating Junction and Storage Temperature Ra      | ange  | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175 | °C   |  |

| THERMAL RESISTANCE RATINGS |                                 |                   |       |      |  |  |
|----------------------------|---------------------------------|-------------------|-------|------|--|--|
| Parameter                  |                                 | Symbol            | Limit | Unit |  |  |
| Junction-to-Ambient        | PCB Mount (TO-263) <sup>d</sup> | R <sub>thJA</sub> | 40    | °C/W |  |  |
| Junction-to-Case (Drain)   |                                 | R <sub>thJC</sub> | 0.4   | C/VV |  |  |

#### Notes:

- a. Package limited.
- b. Duty cycle  $\leq$  1 %.
- c. See SOA curve for voltage derating.
- d. When Mounted on 1" square PCB (FR-4 material).



| Parameter                                     | Symbol               | Test Conditions   | Min. | Тур.  | Max.  | Unit |  |
|---|----------------------|---|------|-------|-------|------|--|
| Static  |                      |   |      |       |       |      |  |
| Drain-Source Breakdown Voltage                | V <sub>(BR)DSS</sub> | $V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$                         | 100  |       |       | V    |  |
| Gate-Threshold Voltage                        | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$                                    | 2    |       | 4     |      |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>     | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$                       |      |       | ± 100 | nA   |  |
|   |                      | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V                          |      |       | 1     |      |  |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>     | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C |      |       | 50    | μA   |  |
|   |                      | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C |      |       | 250   |      |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>   | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$                         | 120  |       |       | Α    |  |
|   |                      | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A                           |      | 0.127 |       |      |  |
| Drain-Source On-State Resistance <sup>a</sup> | r <sub>DS(on)</sub>  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C  |      | 0.130 |       | Ω    |  |
|   |                      | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C  |      | 0.170 |       |      |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>      | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A                           | 25   |       |       | S    |  |
| Dynamic <sup>b</sup>                          |                      |   |      |       |       |      |  |
| Input Capacitance                             | C <sub>iss</sub>     |   |      | 1300  |       | pF   |  |
| Output Capacitance                            | C <sub>oss</sub>     | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz                |      | 260   |       |      |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>     |   |      | 110   |       |      |  |
| Total Gate Charge <sup>c</sup>                | $Q_g$                |   |      |       | 28    | nC   |  |
| Gate-Source Charge <sup>c</sup>               | $Q_{gs}$             | $V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 65 \text{ A}$     |      |       | 4.8   |      |  |
| Gate-Drain Charge <sup>c</sup>                | $Q_{gd}$             |   |      |       | 15    |      |  |
| Gate Resistance                               | $R_g$                |   | 0.5  | 1.7   | 3.3   | Ω    |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>   |   |      | 8     |       |      |  |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>       | $V_{DD} = 100 \text{ V}, R_{L} = 1.5 \Omega$                            |      | 120   |       | ns   |  |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>  | $I_D \cong 65 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$      |      | 25    |       |      |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>       |   |      | 50    |       |      |  |
| Source-Drain Diode Ratings and Cha            | aracteristics 7      | Γ <sub>C</sub> = 25 °C <sup>b</sup>                                     |      |       |       |      |  |
| Continuous Current                            | I <sub>S</sub>       | I <sub>S</sub>  |      | 18    |       | ۸    |  |
| Pulsed Current                                | I <sub>SM</sub>      |   |      | 68    |       | Α    |  |
| Forward Voltage <sup>a</sup>                  | $V_{SD}$             | I <sub>F</sub> = 65 A, V <sub>GS</sub> = 0 V                            |      | 1.0   | 1.5   | V    |  |
| Reverse Recovery Time                         | t <sub>rr</sub>      |   |      | 130   | 200   | ns   |  |
| Peak Reverse Recovery Current                 | I <sub>RM(REC)</sub> | I <sub>F</sub> = 50 A, di/dt = 100 A/μs                                 |      | 8     | 12    | Α    |  |
| Reverse Recovery Charge                       | Q <sub>rr</sub>      |   |      | 0.52  | 1.2   | μC   |  |

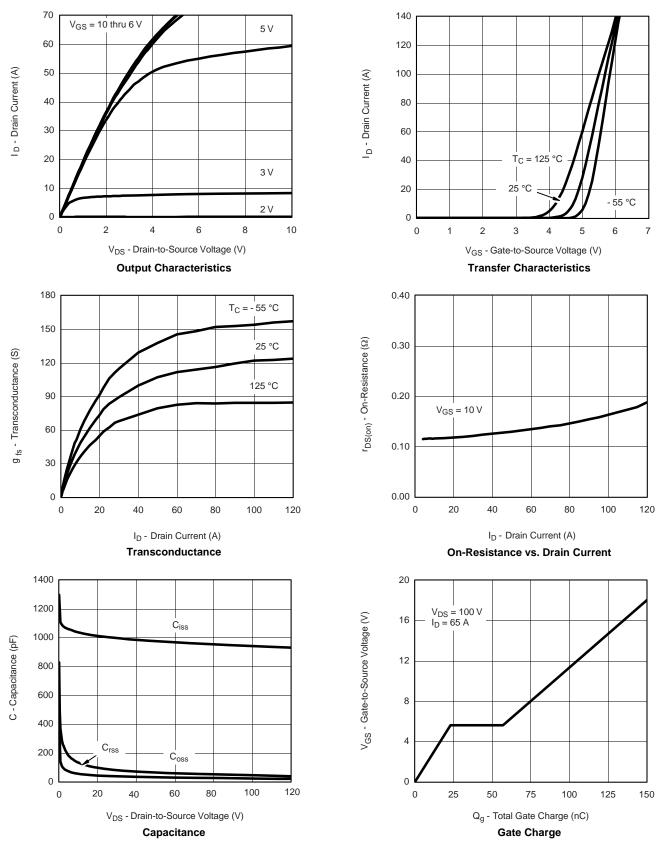
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

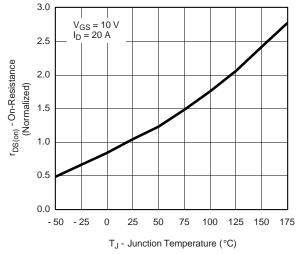


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

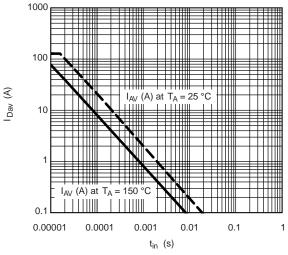




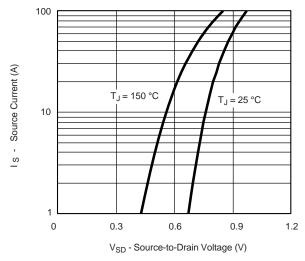
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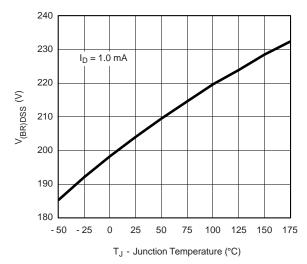
On-Resistance vs. Junction Temperature



**Avalanche Current vs. Time** 



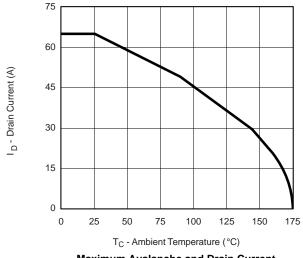
Source-Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature



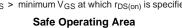
#### THERMAL RATINGS

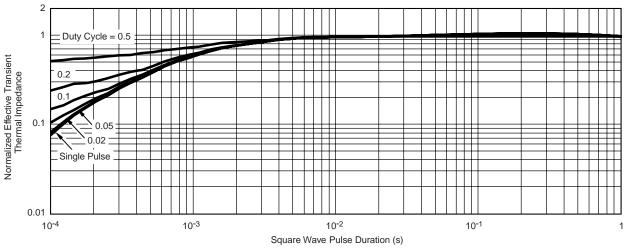


r<sub>DS(on)</sub> Limited 10 µs 100 I<sub>D</sub> - Drain Current (A) 10 T<sub>C</sub> = 25 °C 10 ms 100 ms DC Single Pulse 0.1 0.1 100 1000 10 V<sub>DS</sub> - Drain-to-Source Voltage (V) \*  $V_{GS}$  > minimum  $V_{GS}$  at which  $r_{DS(on)}$  is specified

1000

**Maximum Avalanche and Drain Current** vs. Case Temperature

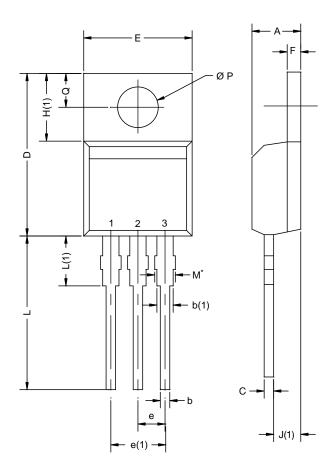




Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-220AB**



|  | MILLIN | IETERS | INC   | HES   |  |
|--|--------|--------|-------|-------|--|
| DIM.   | MIN.   | MAX.   | MIN.  | MAX.  |  |
| А  | 4.25   | 4.65   | 0.167 | 0.183 |  |
| b  | 0.69   | 1.01   | 0.027 | 0.040 |  |
| b(1)   | 1.20   | 1.73   | 0.047 | 0.068 |  |
| С  | 0.36   | 0.61   | 0.014 | 0.024 |  |
| D  | 14.85  | 15.49  | 0.585 | 0.610 |  |
| Е  | 10.04  | 10.51  | 0.395 | 0.414 |  |
| е  | 2.41   | 2.67   | 0.095 | 0.105 |  |
| e(1)   | 4.88   | 5.28   | 0.192 | 0.208 |  |
| F  | 1.14   | 1.40   | 0.045 | 0.055 |  |
| H(1)   | 6.09   | 6.48   | 0.240 | 0.255 |  |
| J(1)   | 2.41   | 2.92   | 0.095 | 0.115 |  |
| L  | 13.35  | 14.02  | 0.526 | 0.552 |  |
| L(1)   | 3.32   | 3.82   | 0.131 | 0.150 |  |
| ØΡ   | 3.54   | 3.94   | 0.139 | 0.155 |  |
| Q  | 2.60   | 3.00   | 0.102 | 0.118 |  |
| ECN: X12-0208-Rev. N, 08-Oct-12<br>DWG: 5471 |        |        |       |       |  |

#### Notes

 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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